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Lead-free solders are used extensively as interconnection materials in electronic assemblies and play a critical role in the global semiconductor packaging and electronics manufacturing industry. Electronic products such as smart phones, notebooks and high performance computers rely on lead-free solder joints to connect IC chip components to printed circuit boards. Lead Free Solder: Mechanics and Reliability provides in-depth design knowledge on lead-free solder elastic-plastic-creep and strain-rate dependent deformation behavior and its application in failure assessment of solder joint reliability. It includes coverage of advanced mechanics of materials theory and experiments, mechanical properties of solder and solder joint specimens, constitutive models for solder deformation behavior; numerical modeling and simulation of solder joint failure subject to thermal cycling, mechanical bending fatigue, vibration fatigue and board-level drop impact tests.

A unique book that describes the practical processes necessary to achieve failure free equipment performance, for quality and reliability engineers, design, manufacturing process and environmental test engineers. This book studies the essential requirements for successful product life cycle management. It identifies key contributors to failure in product life cycle management and particular emphasis is placed upon the importance of thorough Manufacturing Process Capability reviews for both in-house and outsourced manufacturing strategies. The readers' attention is also drawn to the many hazards to which a new product is exposed from the commencement of manufacture through to end of life disposal. Revolutionary in focus, as it describes how to achieve failure free performance rather than how to predict an acceptable performance failure rate (reliability technology rather than reliability engineering) Author has over 40 years experience in the field, and the text is based on classroom tested notes from the reliability technology course he taught at Massachusetts Institute of Technology (MIT), USA Contains graphical interpretations of mathematical models together with diagrams, tables of physical constants, case studies and unique worked examples

This book is a printed edition of the Special Issue "Intermetallics 2016" that was published in Metals

Covering the major topics in lead-free soldering Lead-free Soldering Process Development and Reliability provides a comprehensive discussion of all modern topics in lead-free soldering. Perfect for process, quality, failure analysis and reliability engineers in production industries, this reference will help practitioners address issues in research, development and production. Among other topics, the book addresses: · Developments in process engineering (SMT, Wave, Rework, Paste Technology) · Low temperature, high temperature and high reliability alloys · Intermetallic

compounds · PCB surface finishes and laminates · Underfills, encapsulants and conformal coatings · Reliability assessments In a regulatory environment that includes the adoption of mandatory lead-free requirements in a variety of countries, the book's explanations of high-temperature, low-temperature, and high-reliability lead-free alloys in terms of process and reliability implications are invaluable to working engineers. Lead-free Soldering takes a forward-looking approach, with an eye towards developments likely to impact the industry in the coming years. These will include the introduction of lead-free requirements in high-reliability electronics products in the medical, automotive, and defense industries. The book provides practitioners in these and other segments of the industry with guidelines and information to help comply with these requirements.

The CRC Handbook of Thermal Engineering, Second Edition, is a fully updated version of this respected reference work, with chapters written by leading experts. Its first part covers basic concepts, equations and principles of thermodynamics, heat transfer, and fluid dynamics. Following that is detailed coverage of major application areas, such as bioengineering, energy-efficient building systems, traditional and renewable energy sources, food processing, and aerospace heat transfer topics. The latest numerical and computational tools, microscale and nanoscale engineering, and new complex-structured materials are also presented. Designed for easy reference, this new edition is a must-have volume for engineers and researchers around the globe.

Discusses the growth mechanisms of tin whiskers and the effective mitigation strategies necessary to reduce whisker growth risks This book covers key tin whisker topics, ranging from fundamental science to practical mitigation strategies. The text begins with a review of the characteristic properties of local microstructures around whisker and hillock grains to identify why these particular grains and locations become predisposed to forming whiskers and hillocks. The book discusses the basic properties of tin-based alloy finishes and the effects of various alloying elements on whisker formation, with a focus on potential mechanisms for whisker suppression or enhancement for each element. Tin whisker risk mitigation strategies for each tier of the supply chain for high reliability electronic systems are also described. Discusses whisker formation factors including surface grain geometry, crystallographic orientation-dependent surface grain boundary structure, and the localization of elastic strain/strain energy density distribution Examines how whiskers and hillocks evolve in time through real-time studies of whisker growth with the scanning electron microscope/focused ion beaming milling (SEM/FIB) Covers characterization methods of tin and tin-based alloy finishes such as transmission electron microscopy (TEM), scanning electron microscopy (SEM), and electron backscatter diffraction (EBS-

D) Reviews theories of mechanically-induced tin whiskers with case studies using pure tin and other lead-free finishes shown to evaluate the pressure-induced tin whiskers Mitigating Tin Whisker Risks: Theory and Practice is intended for the broader electronic packaging and manufacturing community including: manufacturing engineers, packaging development engineers, as well as engineers and researchers in high reliability industries.

In semiconductor manufacturing, understanding how various materials behave and interact is critical to making a reliable and robust semiconductor package. Semiconductor Packaging: Materials Interaction and Reliability provides a fundamental understanding of the underlying physical properties of the materials used in a semiconductor package. By tying together the disparate elements essential to a semiconductor package, the authors show how all the parts fit and work together to provide durable protection for the integrated circuit chip within as well as a means for the chip to communicate with the outside world. The text also covers packaging materials for MEMS, solar technology, and LEDs and explores future trends in semiconductor packages. The development of technologies and management of operations is key to sustaining the success of manufacturing businesses, and since the late 1970s, the International Conference on Manufacturing Research (ICMR) has been a major annual event for academics and industrialists engaged in manufacturing research. The conference is renowned as a friendly and inclusive platform that brings together a broad community of researchers who share a common goal. This book presents the proceedings of ICMR2021, the 18th International Conference on Manufacturing Research, incorporating the 35th National Conference on Manufacturing Research, and held in Derby, UK, from 7 to 10 September 2021. The theme of the ICMR2021 conference is digital manufacturing. Within the context of Industrial 4.0, ICMR2021 provided a platform for researchers, academics and industrialists to share their vision, knowledge and experience, and to discuss emerging trends and new challenges in the field. The 60 papers included in the book are divided into 10 parts, each covering a different area of manufacturing research. These are: digital manufacturing, smart manufacturing; additive manufacturing; robotics and industrial automation; composite manufacturing; machining processes; product design and development; information and knowledge management; lean and quality management; and decision support and production optimization. The book will be of interest to all those involved in developing and managing new techniques in manufacturing industry.

The worldwide trend toward lead-free components and soldering is especially urgent in the European Union with the implementation strict new standards in July 2006, and with pending implementation of laws in China and California. This book provides a standard reference guide for engineers who must meet the new regulations, including a broad collection of techniques for lead-free soldering design and manufacture, which up to now have been scattered in difficult-to-find scholarly sources.

This volume presents selected papers from the 2nd International Conference on Mechanical, Manufacturing and Process Plant Engineering (ICMMPPE 2016) which was held from 23rd to 24th November, 2016 in Kuala Lumpur, Malaysia. The proceedings discuss genuine problems of joining technologies that are heart of manufacturing sectors. It discusses the findings of experimental and numerical works from soldering, arc welding to solid state joining technology that faced by current industry.

The theme of conference is Emerging Technologies for Sustainability. Sustainability tends to be problem driven and oriented towards guiding decision making. The goal is to raise the global standard of living without increasing the use of resources beyond

global sustainable levels. The conference is intended to act as a platform for researchers to share and gain knowledge, showcase their research findings and propose new solutions in policy formulation, design, processing and application of green materials, material selection, analysis, green manufacturing, testing and synthesis, thereby contributing to the creation of a more sustainable world.

In this study, the effect of multi-walled carbon nanotubes (MWCNT) reinforcement on joint shear strength and microstructural development of tin-3.0silver-0.5copper (SAC305)/copper solder joint subjected to multiple reflow cycles was investigated. The MWCNT-reinforced SAC305 solder systems (SAC305- x MWCNT; x =0.01, 0.05, 0.1, and 0.5 wt.%) were developed by a mechanical dispersion method. The microstructural, mechanical, and melting properties of SAC305 composite solders were evaluated as a function of different wt.% of MWCNT addition. The melting behavior of composite solders was analyzed using differential scanning calorimetry. The morphology and intermetallic compound growth at the solder joint interface were studied using scanning electron microscopy. The copper/solder/copper micro-lap-shear solder joint specimens reflowed for multiple reflow cycles were systematically characterized to evaluate the joint shear strength. The results showed that the reinforcement in the range of 0.01-0.05 wt.% of MWCNT resulted in the improvement of joint shear strength and better wettability compared to plain SAC305 solder alloy. Amongst all compositions analyzed, SAC305-0.05MWCNT nanocomposite suppressed the intermetallic compound layer growth effectively leading to improvement in the joint shear strength under multiple reflow cycles.

The ITherm Conference series is the leading international venue for scientific and engineering exploration of thermal, thermomechanical, and emerging technology issues associated with electronic devices, packages, and systems

Additive manufacturing (AM) is one of the manufacturing processes that warrants the attention of industrialists, researchers and scientists, because of its ability to produce materials with a complex shape without theoretical restrictions and with added functionalities. There are several advantages to employing additive manufacturing as the primary additive manufacturing process. However, there exist several challenges that need to be addressed systematically. A couple such issues are alloy design and process development. Traditionally alloys designed for conventional cast/powder metallurgical processes were fabricated using advanced AM processes. This is the wrong approach considering that the alloys should be coined based on the process characteristics and meta-stable nature of the process. Hence, we must focus on alloy design and development for AM that suits the AM processes. The AM processes, however, improve almost every day, either in terms of processing capabilities or processing conditions. Hence, the processing part warrants a section that is devoted to these advancements and innovations. Accordingly, the present Special Issue (book) focuses on two aspects of alloy development and process innovations. Here, 45 articles are presented covering different AM processes including selective laser melting, electron beam melting, laser cladding, direct metal laser sintering, ultrasonic consolidation, wire arc additive manufacturing, and hybrid manufacturing. I believe that this Special Issue bears is vital to the field of AM and will be a valuable addition.

Providing a viable alternative to lead-based solders is a major research thrust for the electrical and electronics industries - whilst mechanically compliant lead-based solders have been widely used in the electronic interconnects, the risks to human health and to the environment are too great to allow continued wide-scale usage. Lead-free Solders: Materials Reliability for Electronics

chronicles the search for reliable drop-in lead-free alternatives and covers: Phase diagrams and alloy development Effect of minor alloying additions Composite approaches including nanoscale reinforcements Mechanical issues affecting reliability Reliability under impact loading Thermomechanical fatigue Chemical issues affecting reliability Whisker growth Electromigration Thermomigration Presenting a comprehensive understanding of the current state of lead-free electronic interconnects research, this book approaches the ongoing research from fundamental, applied and manufacturing perspectives to provide a balanced view of the progress made and the requirements which still have to be met. Even though the effect of lead contamination on human health has been known for decades, very little attention has been paid to lead-based solders used in electronics until recently. This comprehensive book examines all the important issues associated with lead-free electronic solder. It collects the work of researchers recognized for their significant scientific contributions in the area.

Assessing the scientific and technological aspects of lead-free soldering, *Lead-Free Soldering in Electronics* considers the necessary background and requirements for proper alloy selection. It highlights the metallurgical and mechanical properties; plating and processing technologies; and evaluation methods vital to the production of lead-free sold

The proposed book will offer comprehensive and versatile methodologies and recommendations on how to determine dynamic characteristics of typical micro- and opto-electronic structural elements (printed circuit boards, solder joints, heavy devices, etc.) and how to design a viable and reliable structure that would be able to withstand high-level dynamic loading. Particular attention will be given to portable devices and systems designed for operation in harsh environments (such as automotive, aerospace, military, etc.) In-depth discussion from a mechanical engineer's viewpoint will be conducted to the key components' level as well as the whole device level. Both theoretical (analytical and computer-aided) and experimental methods of analysis will be addressed. The authors will identify how the failure control parameters (e.g. displacement, strain and stress) of the vulnerable components may be affected by the external vibration or shock loading, as well as by the internal parameters of the infrastructure of the device. Guidelines for material selection, effective protection and test methods will be developed for engineering practice.

Solders have given the designer of modern consumer, commercial, and military electronic systems a remarkable flexibility to interconnect electronic components. The properties of solder have facilitated broad assembly choices that have fueled creative applications to advance technology. Solder is the electrical and mechanical "glue" of electronic assemblies. This pervasive dependency on solder has stimulated new interest in applications as well as a more concerted effort to better understand materials properties. We need not look far to see solder being used to interconnect ever finer geometries. Assembly of micropassive discrete devices that are hardly visible to the unaided eye, of silicon chips directly to ceramic and plastic substrates, and of very fine peripheral leaded packages constitute a few of solder's uses. There has been a marked increase in university research related to solder. New electronic packaging centers stimulate applications, and materials engineering and science departments have demonstrated a new vigor to improve both the materials and our understanding of them. Industrial research and development continues to stimulate new application, and refreshing new packaging ideas are emerging. New handbooks have been published to help both the neophyte and seasoned packaging engineer.

This collection features papers presented at the 148th Annual

Meeting & Exhibition of The Minerals, Metals & Materials Society.

This book provides some of the most advanced research observations and in-depth knowledge behind lead-free soldering. Readers will find a description of different cutting-edge techniques used for improving the reliability of interconnects manufacturing. Some of the most unconventional topics covered in this book include solder joint formation for microelectronic devices at room temperature and the possibility of soldering ceramic materials, which is limited due to the poor wettability of ceramic substrates with commercial solders following classical soldering techniques. We also discuss the possibilities of nanoscale preparation of solder joints for bringing down the processing temperature so that it does not affect the packaging technologies. Readers will find that precise, systematic discussion of solder joint formation and its interfacial characterization has been depicted for each technique used in different chapters. This book is of interest to both fundamental researchers and also to practicing scientists and will prove invaluable to all those working in industry and academia.

MEMS and Nanotechnology, Volume 5: Proceedings of the 2013 Annual Conference on Experimental and Applied Mechanics, the fifth volume of eight from the Conference, brings together contributions to this important area of research and engineering. The collection presents early findings and case studies on a wide range of areas, including: Microelectronics Packaging Single Atom-/Molecule Mechanical Testing MEMS Devices & Fabrication In-Situ Mechanical Testing Nanoindentation Experimental Analysis of Low-Dimensional Materials for Nanotechnology

This book highlights recent research progress in lead (Pb)-free solder technology, focusing on materials development, processing, and performances. It discusses various Pb-free solder materials' development, encompassing composite solders, transient liquid phase sintering, and alloying. The book also details various Pb-free solder technology processing and performances, including flux modification for soldering, laser soldering, wave soldering, and reflow soldering, while also examining multiple technologies pertaining to the rigid and flexible printed circuit board (PCB). Some chapters explain the materials characterization and modeling techniques using computational fluid dynamics (CFD). This book serves as a valuable reference for researchers, industries, and stakeholders in advanced microelectronic packaging, emerging interconnection technology, and those working on Pb-free solder.

Lead-free Electronics provides guidance on the design and use of lead-free electronics as well as technical and legislative perspectives. All the complex challenges confronting the electronics industry are skillfully addressed: * Complying with state legislation * Implementing the transition to lead-free electronics, including anticipating associated costs and potential supply chain issues * Understanding intellectual property issues in lead-free alloys and their applications, including licensing and infringement * Implementing cost effective manufacturing and testing * Reducing risks due to tin whiskers * Finding lead-free solutions in harsh environments such as in the automotive and telecommunications industries * Understanding the capabilities and limitations of conductive adhesives in lead-free interconnects * Devising solutions for lead-free, flip-chip interconnects in high-performance integrated circuit products Each chapter is written by leading experts in the field and carefully edited to ensure a consistent approach. Readers will find all the latest information, including the most recent data on cyclic thermomechanical deformation properties of lead-free SnAgCu alloys and a comparison of the properties of standard Sn-Pb versus lead-free alloys, using the energy partitioning approach. With legislative and market pressure to eliminate the use of lead in electronics manufacturing, this timely publica-

tion is essential reading for all engineers and professionals in the electronics industry.

This unique book provides an up-to-date overview of the concepts behind lead-free soldering techniques. Readers will find a description of the physical and mechanical properties of lead-free solders, in addition to lead-free electronics and solder alloys. Additional topics covered include the reliability of lead-free soldering, tin whiskering and electromigration, in addition to emerging technologies and research.

Metals—Advances in Research and Application: 2012 Edition is a ScholarlyEditions™ eBook that delivers timely, authoritative, and comprehensive information about Metals. The editors have built Metals—Advances in Research and Application: 2012 Edition on the vast information databases of ScholarlyNews.™ You can expect the information about Metals in this eBook to be deeper than what you can access anywhere else, as well as consistently reliable, authoritative, informed, and relevant. The content of Metals—Advances in Research and Application: 2012 Edition has been produced by the world's leading scientists, engineers, analysts, research institutions, and companies. All of the content is from peer-reviewed sources, and all of it is written, assembled, and edited by the editors at ScholarlyEditions™ and available exclusively from us. You now have a source you can cite with authority, confidence, and credibility. More information is available at <http://www.ScholarlyEditions.com/>.

Volume is indexed by Thomson Reuters CPCI-S (WoS).

This book is about solders and their composition and focuses on material characterizations and the methods used to make alloys and determine their structures, physical properties and applications. Physical properties and the factors that control them and theoretical verification are the main contents of this book. Corrosion of solders is included in the coverage of the properties related to solder composition and mechanical properties.

This book covers all aspects of physical vapor deposition (PVD) process technology from the characterizing and preparing the substrate material, through deposition processing and film characterization, to post-deposition processing. The emphasis of the book is on the aspects of the process flow that are critical to economical deposition of films that can meet the required performance specifications. The book covers subjects seldom treated in the literature: substrate characterization, adhesion, cleaning and the processing. The book also covers the widely discussed subjects of vacuum technology and the fundamentals of individual deposition processes. However, the author uniquely relates these topics to the practical issues that arise in PVD processing, such as contamination control and film growth effects, which are also rarely discussed in the literature. In bringing these subjects together in one book, the reader can understand the interrelationship between various aspects of the film deposition processing and the resulting film properties. The author draws upon his long experience with developing PVD processes and troubleshooting the processes in the manufacturing environment, to provide useful hints for not only avoiding problems, but also for solving problems when they arise. He uses actual experiences, called "war stories", to emphasize certain points. Special formatting of the text allows a reader who is already knowledgeable in the subject to scan through a section and find discussions that are of particular interest. The author has tried to make the subject index as useful as possible so that the reader can rapidly go to sections of particular interest. Extensive references allow the reader to pursue subjects in greater detail if desired. The book is intended to be both an introduction for those who are new to the field and a valuable resource to those already in the field. The discussion of transferring technology between R&D and manufacturing provided in Ap-

pendix 1, will be of special interest to the manager or engineer responsible for moving a PVD product and process from R&D into production. Appendix 2 has an extensive listing of periodical publications and professional societies that relate to PVD processing. The extensive Glossary of Terms and Acronyms provided in Appendix 3 will be of particular use to students and to those not fully conversant with the terminology of PVD processing or with the English language.

The 16th International Symposium on MEMS and Nanotechnology, Volume 5 of the Proceedings of the 2015 SEM Annual Conference & Exposition on Experimental and Applied Mechanics, the fifth volume of nine from the Conference, brings together contributions to this important area of research and engineering. The collection presents early findings and case studies on a wide range of areas, including: Microscale and Microstructural Effects on Mechanical Behavior Dynamic Micro/Nanomechanics In-situ Techniques Mechanics of Graphene Indentation and Small Scale Testing MEMS

This book focuses on the assembly and reliability of lead-free solder joints. Both the principles and engineering practice are addressed, with more weight placed on the latter. This is achieved by providing in-depth studies on a number of major topics such as solder joints in conventional and advanced packaging components, commonly used lead-free materials, soldering processes, advanced specialty flux designs, characterization of lead-free solder joints, reliability testing and data analyses, design for reliability, and failure analyses for lead-free solder joints. Uniquely, the content not only addresses electronic manufacturing services (EMS) on the second-level interconnects, but also packaging assembly on the first-level interconnects and the semiconductor back-end on the 3D IC integration interconnects. Thus, the book offers an indispensable resource for the complete food chain of electronics products.

Failure analysis is the preferred method to investigate product or process reliability and to ensure optimum performance of electrical components and systems. The physics-of-failure approach is the only internationally accepted solution for continuously improving the reliability of materials, devices and processes. The models have been developed from the physical and chemical phenomena that are responsible for degradation or failure of electronic components and materials and now replace popular distribution models for failure mechanisms such as Weibull or lognormal. Reliability engineers need practical orientation around the complex procedures involved in failure analysis. This guide acts as a tool for all advanced techniques, their benefits and vital aspects of their use in a reliability programme. Using twelve complex case studies, the authors explain why failure analysis should be used with electronic components, when implementation is appropriate and methods for its successful use. Inside you will find detailed coverage on: a synergistic approach to failure modes and mechanisms, along with reliability physics and the failure analysis of materials, emphasizing the vital importance of cooperation between a product development team involved the reasons why failure analysis is an important tool for improving yield and reliability by corrective actions the design stage, highlighting the 'concurrent engineering' approach and DfR (Design for Reliability) failure analysis during fabrication, covering reliability monitoring, process monitors and package reliability reliability testing after fabrication, including reliability assessment at this stage and corrective actions a large variety of methods, such as electrical methods, thermal methods, optical methods, electron microscopy, mechanical methods, X-Ray methods, spectroscopic, acoustical, and laser methods new challenges in reliability testing, such as its use in microsystems and nanostructures This practical yet comprehensive reference is useful for manufacturers and engineers involved in the de-

sign, fabrication and testing of electronic components, devices, ICs and electronic systems, as well as for users of components in complex systems wanting to discover the roots of the reliability flaws for their products.

Compliance with RoHS requirements has necessitated the development of high reliability alternatives to SAC305 lead-free solder. Bismuth containing ternary and quaternary alloys are emerging as an attractive lead-free high reliability solder. A particular point of interest is the solvus temperature \hat{a} the point above which Bi will form a solid solution, and below which Bi will precipitate out of the matrix. The solvus temperature of these solders was determined using a novel differential scanning calorimetry (DSC) method. A study was conducted to characterize the effects of aging above- and below-solvus on microstructure and mechanical properties. Metallographic analysis showed that above-solvus aging improved bismuth distribution as well as reduced grain size. It was concluded that above-solvus aging could be used as a restorative treatment for in service electronics. Nano-indentation was used to collect creep and hardness data, and it was found that above-solvus aging had a positive effect on mechanical properties.

The papers collected in this special issue clearly reflect the modern research trends in materials science. These fields of specific attention are high-Mn TWIP steels, high-Cr heat resistant steels, aluminum alloys, ultrafine grained materials including those developed by severe plastic deformation, and high-entropy alloys. The major portion of the collected papers is focused on the mechanisms of microstructure evolution and the mechanical properties of metallic materials subjected to various thermo-mechanical, deformation or heat treatments. Another large portion of the studies is aimed on the elaboration of alloying design of advanced steels and alloys. The changes in phase content, transformation and particle precipitation and their effect on the properties are also broadly presented in this collection, including the microstructure/property changes caused by irradiation.

ECTC is the premier international conference sponsored by the IEEE Components, Packaging and Manufacturing Society ECTC paper comprise a wide spectrum of topics, including 3D packaging, electronic components, materials, assembly, interconnections, device and system packaging, optoelectronics, reliability, and simulation

This handbook provides the most comprehensive, up-to-date and easy-to-apply information on the physics, mechanics, reliability and packaging of micro- and opto-electronic materials. It details their assemblies, structures and systems, and each chapter contains a summary of the state-of-the-art in a particular field. The book provides practical recommendations on how to apply cur-

rent knowledge and technology to design and manufacture. It further describes how to operate a viable, reliable and cost-effective electronic component or photonic device, and how to make such a device into a successful commercial product.

"As the traditional eutectic SnPb solder alloy has been outlawed, the electronic industry has almost completely transitioned to the lead-free solder alloys. The conventional SAC305 solder alloy used in lead-free electronic assembly has a high melting and processing temperature with a typical peak reflow temperature of 245°C which is almost 30°C higher than traditional eutectic SnPb reflow profile. Some of the drawbacks of this high melting and processing temperatures are yield loss due to component warpage which has an impact on solder joint formation like bridging, open defects, head on pillow, and other drawbacks which include circuit board degradation, economic and environmental factors, and brittle failure defects in the circuit board like pad cratering. To overcome this, a detailed study has been carried out on low temperature lead-free solder paste that utilizes Bi bearing alloys. Three low temperature lead-free solder pastes, Sn-58Bi, Sn-57Bi-1Ag and Sn-40Bi-Cu-Ni with the melting temperatures of 138°C (which is 45°C below eutectic SnPb and 79°C below SAC) were printed on Cu-OSP finish test boards. These pastes were then assembled with SAC305, Sn99CN and Sn100C solder spheres. The range of Bi concentrations for various mixtures used in this study was calculated to be in the range of 2 to 4 wt%. The mixtures were reflowed under two different low temperatures reflow profiles; (a) a traditional SnPb profile with a peak temperature 217°C and (b) a low temperature SnBi profile with a peak temperature 177°C (recommended by the paste manufacturer). After the assembly process, the mixed solder joints were shear tested to study the failure modes and shear strength at rate of 27.50mils/sec. Cross sectioning was performed to evaluate the possible microstructural changes at room temperature and after aging conditions that may have led to the changes in failure mode observed in shear testing. The isothermal aging condition used in the study is 125°C for 200 hours, which mimics 21 years of field storage at 25°C degrees using Arrhenius extrapolation for Cu6Sn5 intermetallic formation. Our study suggests that high temperature reflow profile (217°C peak profile) had better mechanical strength than the low temperature reflow profile (177°C peak profile). A metallurgical explanation for the improvement is presented in this paper. Thus, this paper describes that by generating a robust reflow assembly process for SnBi solder paste, the shear strength can be increased, cost of manufacturing can be reduced and high temperature assembly process (SAC) issues can be minimized which may improve product yield in production."--Abstract.